

PRODUCTION DATA SHEET

ABSOLUTE MAXIMUM RATINGS

Input Voltage (V _{IN})	0.3V to +7V
Enable Input	\cdot -0.3V to V_{IN} +.3V
Output Current (I _{OUT})	
Operating Temperature Range	40 to +125 °C
Maximum Junction Temperature (T _J)	150 °C
RoHS Compliant / Pb-free Peak Package Solder	
Reflow Temperature (40 second max. exposure)	260°C (+0, -5)

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

PACKAGE PIN OUT 1 5 2 4 SE PACKAGE (Top View) RoHS / Pb-free 100% Matte Tin Pin Finish

THERMAL DATA

5-PIN SOT-23 PACKAGE

Thermal Resistance – Junction to Ambient, θ_{JA}	
Two – Layer Board	220°C/W
■ Four – Layer Board	220°C/W

Junction Temperature Calculation: $T_J = T_A + (P_D x \theta_{JA})$.

The θ_{JA} numbers are guidelines for the thermal performance of the device/pe-board system. All of the above assume no ambient airflow.

FUNCTIONAL PIN DESCRIPTION					
PIN NAME	PIN Number	DESCRIPTION			
VIN	1	Unregulated input supply voltage			
GND	2	Ground Pin			
ENABLE	3	Enable Control Input, Enable High			
CBY/ADJUST	4	Reference bypass input. Adding an additional external capacitor reduces output noise. Or adjust control input for LX8211-00.			
VOUT	5	Regulated output voltage. Regulator stability is achieved with external capacitor of 1uF			

APPLICATION

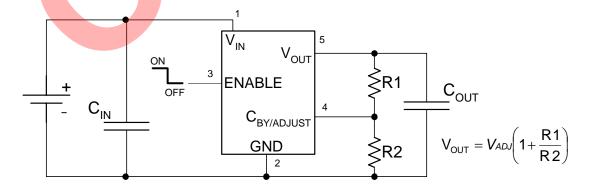


Figure 1 – Output Voltage Set Externally



PRODUCTION DATA SHEET

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	LX8211-xx			Units	
r arameter	Mir		Тур Мах		Uillis	
Input Operating Voltage Range (Note 1)	V _{IN}	2.5		6	V	
Enable Input Voltage Range	ENABLE	0		V _{IN} + .3V		
Continuous Output Current Range	I _{OUT}	.1		150	mA	
Input Capacitor (V _{IN} to GND)	C _{IN}	1.0	1.0*		μF	
Output Capacitor (V _{OUT} to GND)	Соит	1.0	2.2*		μF	

Note 1: The minimum V_{IN} has to meet two conditions $V_{\text{IN}}\!\!\geq\!\!2.5V$ and $V_{\text{IN}}\!\!\geq\!\!V_{\text{OUT}}\!\!+\!\!V_{\text{DROPOUT}}.$

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, the following specifications apply over the operating ambient temperature -40°C $\leq T_A \leq 125$ °C except where otherwise noted. Test conditions: $V_{IN} = V_{OUT} + 0.5V$; $I_{OUT} = 10$ mA; $C_{IN} = 1$ uF; $C_{OUT} = 1$ uF; $T_J = T_A$ using low duty cycle pulse testing methods.

Parameter	Symbol	Test Conditions		LX8211-XX		
Farameter	Symbol	rest conditions	Min	Тур	Max	Units
Output Voltage (-25, -27, -28, -30, -33)	Vo	T _J = 25°C	-1		1	%V _{NOM}
Output Voltage (-25, -27, -26, -30, -35)	V _O	$I_{OUT} = 0mA \text{ to } 150mA, V_{IN} = V_{OUT} + .5V \text{ to } 6V$	-2.5		2.5	%V _{NOM}
Adjust Reference Voltage (-00)	V_{ADJ}	T _J = 25°C	1.163		1.187	V
	▼ ADJ	I_{OUT} = 0mA to 150mA, V_{IN} = 2.85V to 6V	1.14	1.175	1.20	v
Line Regulation $\begin{pmatrix} \Delta V_{0} \\ \Delta V_{IN} \end{pmatrix}$	V_{RV}	V _{IN} : V _{OUT} + 0.5 TO 6 VOLTS, I _{OUT} =0.1mA		0.04	0.15	%/V
Load Regulation $\begin{pmatrix} \Delta V_0 \\ \Delta I_0 \end{pmatrix}$	V_{RI}	$T_J = 25$ °C, I_{OUT} : 0.5 TO 150mA		0.5	1.0	%V _{NOM}
Load Regulation ΔI_0		I _{ОUТ} : 0.5 ТО 150mA			1.5	%V _{NOM}
Dropout Voltage $(V_{IN} - V_O)$ (Note2)	V _{DO}	$I_{LOAD} = 1$ mA, $\Delta_{VO} = -1$ %			0.05	V
		$I_{LOAD} = 50$ mA, $\Delta_{VO} = -1\%$		0.1	0.175	V
		$I_{LOAD} = 100 \text{mA}, \Delta_{VO} = -1\%$		0.175	0.3	V
		I_{LOAD} = 150mA, Δ_{VO} = -1%		0.25	0.4	V
Ground Pin Current	I_{GND}	Enable = Hi		140	220	μΑ
Glound Fin Current	I _{STBY}	Enable = Low			1	μΑ
Adjust Input Bias Current	I_{ADJ}	V _{ADJ} = 1.175V			100	nA
Enable Pin Current	I _{EN}	$V_{EN} = V_{IN}$			100	nA
Enable Threshold	V _{IH}		2.0			V
Enable Threshold	VIL				0.4	V
Short Circuit Current Limit	IOUTSC	V _{OUT} = 0V		400		mA
Power Supply Rejection Ratio	PSRR	T _J = 25°C, f = 120Hz		50		dB
Output Noise	e _N	T _J = 25°C, C _{OUT} = 10uF,C _{BYPASS} = 470 pF		50		μV
Thermal Shutdown Temperature	T _{SD}			170		°C

Note 2: Dropout voltage is defined as the input to output differential at which the output voltage drops 1% below the nominal value.

^{*} Size your output capacitor to meet the transient loading requirement. If you have a very dynamic load, a lower ESR and larger value capacitor will improve the response to these load steps.



PRODUCTION DATA SHEET

ENABLE Control Logic R_B

Figure 2 – Simplified Fixed Version Block Diagram (LX8211-25 / 27 / 28/ 30/ 33ISE)

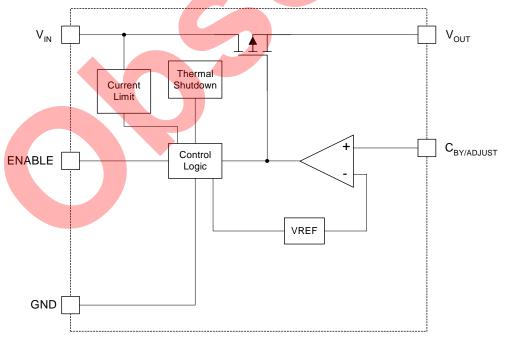


Figure 3 – Simplified Adjustable Version Block Diagram (LX8211-00ISE)



PRODUCTION DATA SHEET

APPLICATION INFORMATION

Description

The LX8211 is a family of LDO (Low Drop-Out) linear regulators in a small SOT-23 Package, which provides a compact and cost effective solution. The family includes several fixed output voltages, along with an adjustable version. The internal PMOS power device provides low dropout regulation with fast line and load transient response. It also includes internal current limit and thermal shutdown circuitry. In this section you will find information about selection of external capacitors, thermal and layout consideration.

Input Capacitor

To improve load transient response and noise rejection a bypass capacitor is recommended, but it is not required for stability. There are no requirements for the ESR (Equivalent Series Resistor) on the input capacitor, but tolerance and temperature coefficient must be considered when selecting the capacitor to ensure the capacitor will be around 1uF over the entire operating temperature range. For LX8211 connect ceramic type capacitor (1uF) between $V_{\rm IN}$ and ground.

Output Capacitor

To maintain a constant output voltage a feedback loop is necessary. The feedback loop causes a well known a phase shift, the amount of phase shift determines the loop stability. Therefore, LX8211 like any low-dropout regulator, requires an output capacitor with low ESR (Equivalent Series Resistor) connected between VOUT and GND to stabilize the internal control loop. For the LX8211 a ceramic, tantalum or electrolytic capacitor with the minimum recommended capacitance value at 1.0 uF with ESR between $5m\Omega$ and 1Ω will satisfy the stability for whole operating range.

Bypass Capacitor (Optional) / Adjustable Output Voltage

The LX8211 includes the extra Bypass pin to help further reduce the already low output noise in the regulator. If the output noise requirement meets the specification, omit the bypass capacitor, that's because the capacitor impacts the start up time which is inversely proportional to the size of bypass capacitor. The bypass capacitor reduces the regulator phase margin, therefore it requires a larger output capacitor to maintain stability.

The LX8211-00 adjustable regulator's output voltage can be externally set by connecting the ADJ pin to an external resistor divider (See Figure 1). The output voltage can be calculated using:

$$V_{OUT} = V_{ADJ} \left(1 + \frac{R1}{R2} \right)$$

Enable

The Enable pin allows the LX8211 to be turned on and off. The Enable pin is compatible with standard TTL-CMOS levels. A logic zero (0.4V) on the Enable pin shuts the LX8211 off and reduces the supply current to less than 1uA. Pulling the Enable input high (2.0V) causes normal operation to resume. If the Enable feature is not used, this pin can be connected to $V_{\rm IN}$.

Minimum Load Requirement

The LX8211 is stable even at zero load; no minimum load is required for operation, which is especially important in keep-alive applications. However line regulation is improved with a minimum load of 100uA.

Temperature Protection

The thermal protection shuts the LX8211 down when the junction temperature exceeds approximately 150°C, there is no appreciable thermal hysteresis.

Short Circuit Current Protection

The LX8211 includes over current protection, when the output load current exceeds typically 400mA the circuit forces the regulator decrease in output.

Thermal Consideration

Thermal shutdown protects the integrated circuit from thermal overload caused from a rise in junction temperature during power dissipation. This means of protection is intended for fault protection only and not as a means of current or power limiting during normal application usage. Proper thermal evaluation should be done to ensure that the junction temperature dose not exceed it's maximum rating. Operating at the maximum T_J of 150°C can impact reliability. Due to variation in individual device electrical characteristics and thermal resistance, the built in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.

Power dissipation for regulator can be calculated using the following equation:

$P_D = (V_{IN(MAX)} - V_{OUT(MIN)}) * I_{OUT(MAX)}$

(Note: power dissipation resulting from quiescent current is negligible)

For the SOT23 package, thermal resistance, θ_{JA} is 220°C/W when mounted on a FR4 copper clad PCB. Junction temperature of the integrated circuit can be calculated using:

$$T_J = T_A + T_{RISE}$$
, substituting: $T_A + (P_D * \theta_{JA})$.

An example: Given conditions: $T_A = 60$ °C, $V_{IN} = 4.2$ V, $V_{OUT} = 2.7$ V, $I_{OUT} = 100$ mA.

Calculated values:

Total Power dissipation $P_{D(total)} = (4.2-2.7) \text{ V} * 0.1 \text{A} = 0.15 \text{W}$ Junction Temperature $T_J = 60^{\circ}\text{C} + (0.15 \text{W} * 220^{\circ}\text{C/W}) = 93^{\circ}\text{C}$

Layout Consideration:

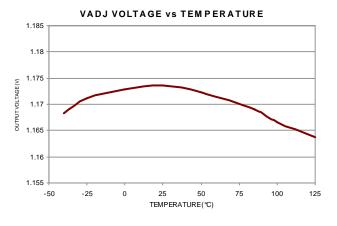
The layout must be done with low impedance paths for $V_{\rm IN}$, $V_{\rm OUT}$ and Ground by applying sufficient wide traces to avoid voltage drops and pick up noise. Adding an area of PCB copper to the GND pin (pin2) will reduce the overall θ_{JA} since it is thermally connected to the device substrate. This will lower the device junction temperature improving the overall output accuracy. The input/output capacitors must be placed as close as possible to the voltage regulator output pin. To allow the same voltage reference for all circuits, use a star configuration from the output capacitor to the different loads.

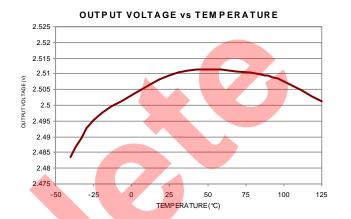


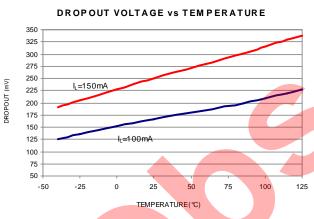
PRODUCTION DATA SHEET

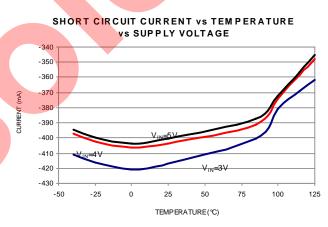
TYPICAL CHARACTERISTICS

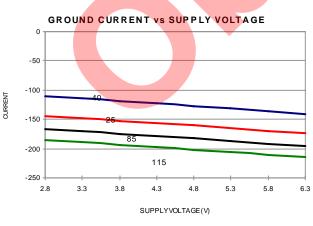
Typical performance characteristics, unless otherwise specified are: $C_{IN} = C_{OUT} = 1 \mu F$, $C_{BY} = 470 pF$, $V_{IN} = V_{OUT} + 0.5 V$, $I_{OUT} = 10 mA$, $T_A = 25 ^{\circ}C$, ENABLE is tied to V_{IN} .

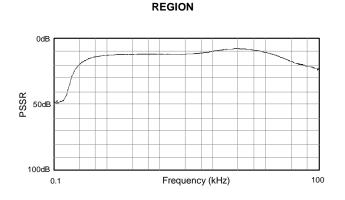












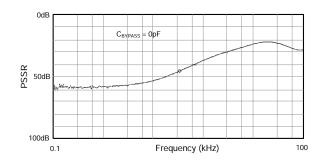
POWER SUPPLY / RIPPLE REJECTION vs FREQUENCY DROPUT



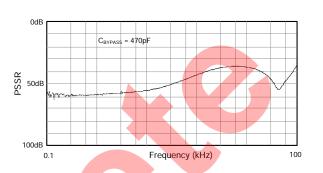
PRODUCTION DATA SHEET

TYPICAL CHARACTERISTICS (CONTINUED)

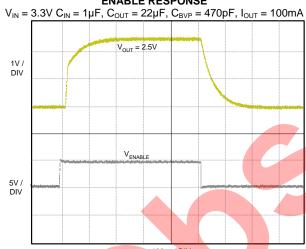
POWER SUPPLY RIPPLE REJECTION VS. FREQUENCY



POWER SUPPLY / RIPPLE REJECTION VS. FREQUENCY

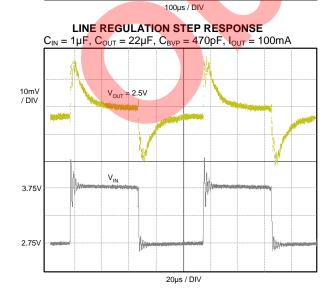


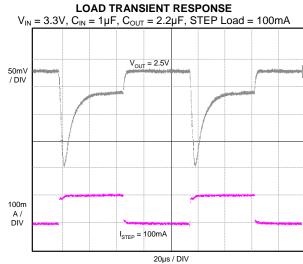
ENABLE RESPONSE



LOAD TRANSIENT RESPONSE







Copyright © 2000 Rev. 1.0d, 2007-08-29

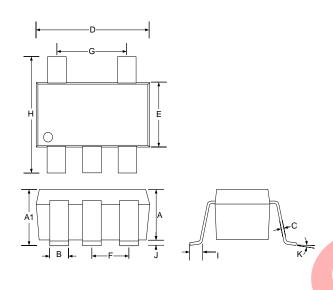


PRODUCTION DATA SHEET

PACKAGE DIMENSION

SE

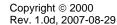
5 Pin Plastic SOT-23



Dim	MILLIMETERS		INCHES		
Dilli	MIN	MAX	MIN	MAX	
Α	0.90	1.30	0.035	0.051	
A1	0.90	1.45	0.035	0.057	
В	0.25	0.50	0.010	0.020	
С	0.09	0.20	0.004	800.0	
D	2.80	3.10	0.110	0.122	
E	1.50	1.75	0.059	0.069	
F	0.95	0.95 BSC		BSC	
G	1.90	BSC	0.075	BSC	
H	2.60	3.00	0.102	0.118	
	0.35	0.55	0.014	0.022	
J	0.00	0.15	0.000	0.006	
K	10° I	MAX	10° MAX		

Note:

1. Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.

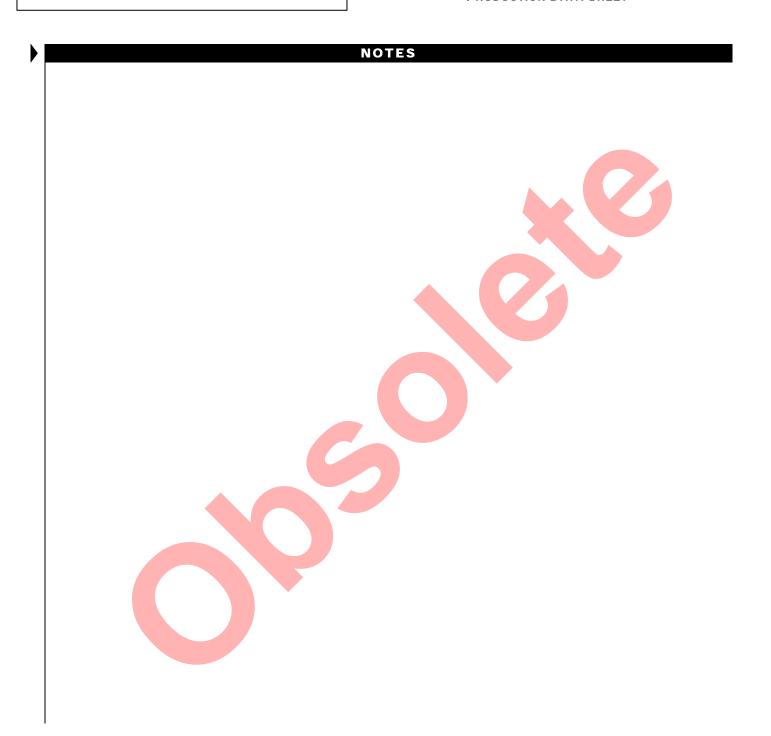




LX8211

150mA CMOS Low Dropout Regulator

PRODUCTION DATA SHEET



PRODUCTION DATA – Information contained in this document is proprietary to Microsemi and is current as of publication date. This document may not be modified in any way without the express written consent of Microsemi. Product processing does not necessarily include testing of all parameters. Microsemi reserves the right to change the configuration and performance of the product and to discontinue product at any time.